

Pending Claims

1. - 8. Cancelled.

9. (Previously Amended) An article comprising:

a chip stack comprising a plurality of integrated circuit chips ("IC") that are disposed in spaced and parallel relation to one another, each said IC having two major surfaces, four sides, an active device area and a kerf surrounding said active device area, wherein:

at least a portion of said kerf along one of said sides of each IC is removed defining a foreshortened side thereof;

said foreshortened side of said ICs are aligned;

a plurality of bumps are disposed along said foreshortened side between opposing major surfaces of adjacent ICs;

each said bump is disposed partially in said active device area of said IC and partially beyond an edge of said foreshortened side.

10. (Previously Amended) The article of claim 9 further comprising a first plurality of bonding pads that are disposed on one of said opposing major surfaces of said adjacent ICs, wherein said plurality of bumps are disposed on said plurality of bonding pads.

11. (Previously Amended) The article of claim 10 wherein said bonding pads are electrically connected to electrical circuitry.

12. (Previously Amended) The article of claim 9 further comprising adhesive that is disposed in a space between said opposing major surfaces of said adjacent ICs.

13. (Previously Amended) The article of claim 12 wherein said adhesive is an epoxy.

14. (Previously Amended) The article of claim 9 wherein said chip stack defines a first level electronics package, and further comprising a second level electronics package, wherein said second level electronics package is attached to said first level electronics package at said bumps.

15. (Previously Amended) The article of claim 14 wherein said second level electronics package is a printed circuit board.

16. (Currently Amended) An article comprising:
a plurality of integrated circuit ("IC") chips, each said IC chip having:
 electrical leads extending to one side thereof;
 bonding pads disposed at said one side, wherein said bonding pads are electrically connected to said electrical leads;
 bumps disposed on said bonding pads, wherein **said bumps have an oblong shape and wherein** an exposed portion of each of said bumps extends beyond said one side and beyond said bonding pads; wherein:
 said plurality of IC chips are secured to one another at major surfaces thereof forming a chip stack;
 said one side of each said IC chip is aligned with said one side of all other IC chips in said chip stack, said aligned sides defining an access plane;
 said exposed portion of each of said bumps extends beyond said access plane.

17. Cancelled

18. (Previously Amended) The article of claim 16 further comprising a substrate, said substrate having a plurality of electrically-conductive pads, wherein said exposed portion of said bumps is attached to said pads.

19. (Previously Amended) The article of claim 18 wherein said substrate comprises a printed circuit board.